



00-001

CAU 2812

April 12, 2001

TO: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

#3 1/2
8-22-02
Payton

TC 2800 MAIL ROOM

RECEIVED
APR 30 2001

Subject:

Serial No. 09/773,872 02/02/00

Richard Bullock, David P. Jones

METHOD OF FABRICATING A GATE
DIELECTRIC LAYER FOR A THIN FILM
TRANSISTOR

Grp. Art Unit: 2812

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.


U.S. Patent 6,124,171 to Arghavani et al., "Method of
Forming Gate Oxide Having Dual Thickness by Oxidation Process",
discusses a dual gate oxide process.

U.S. Patent 6,121,095 to Tai et al., "Method for
Fabricating Gate Oxide", discusses a N anneal of a gate oxide.

The following five U.S. Patents disclose gate oxide processes:

- 1) U.S. Patent 6,124,210 to Chino et al., "Method of Cleaning Surface of Substrate and Method of Manufacturing Semiconductor Device".
- 2) U.S. Patent 6,040,207 to Gardner et al., "Oxide Formation Technique Using Thin Film Silicon Deposition".
- 3) U.S. Patent 5,940,736 to Brady et al., "Method for Forming a High Quality Ultrathin Gate Oxide Layer".
- 4) U.S. Patent 5,712,208 to Tseng et al., "Methods of Formation of Semiconductor Composite Gate Dielectric Having Multiple Incorporated Atomic Dopants".
- 5) U.S. Patent 4,851,370 to Doklan et al., "Fabricating a Semiconductor Device with Low Defect Density Oxide".

Sincerely,


Stephen B. Ackerman,
Reg. No. 37761

